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(12) **United States Design Patent**  
**Karasawa**

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(54) **CASSETTE RECEIVING TOOL FOR SEMICONDUCTOR MANUFACTURING APPARATUS**

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(\*\*) Term: **15 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (12) Cl.** ..... **13-03**

(52) **U.S. Cl.**  
USPC ..... **D13/182**

(58) **Field of Classification Search**

USPC ..... D13/182, 184, 199; D15/144, 144.1, D15/199, 140; 294/1.1, 2, 6, 12, 15, 16, 294/26-34, 49, 55.5, 87.1; 16/114 R; 118/500, 503, 728; 206/328, 334, 445, 206/454; 414/416, 217, 940, 331, 935, 414/939; 451/364; 269/903; 248/694  
CPC ..... B65G 49/07; H01L 21/673; H01L 21/67; H01L 21/67353; H01L 21/67769; H01L 21/67775; H01L 21/67379; H01L 23/32; B65D 25/28

See application file for complete search history.

(56) **References Cited**

**U.S. PATENT DOCUMENTS**

5,947,675 A \* 9/1999 Matsushima ..... H01L 21/67775  
414/416.08  
5,947,677 A \* 9/1999 Matsushima ..... H01L 21/67769  
414/609

6,152,680 A \* 11/2000 Howells ..... H01L 21/6732  
414/781  
6,270,307 B1 \* 8/2001 Sinha ..... H01L 21/67313  
198/394  
6,595,841 B2 \* 7/2003 Lai ..... B24B 37/345  
248/694  
D665,759 S \* 8/2012 Sato ..... D13/199  
D674,365 S \* 1/2013 Kajiwara ..... D13/182  
D695,240 S \* 12/2013 Iida ..... D13/182  
D701,498 S \* 3/2014 Iida ..... D13/182  
8,676,375 B2 \* 3/2014 Kraus ..... H01L 21/67259  
700/213

\* cited by examiner

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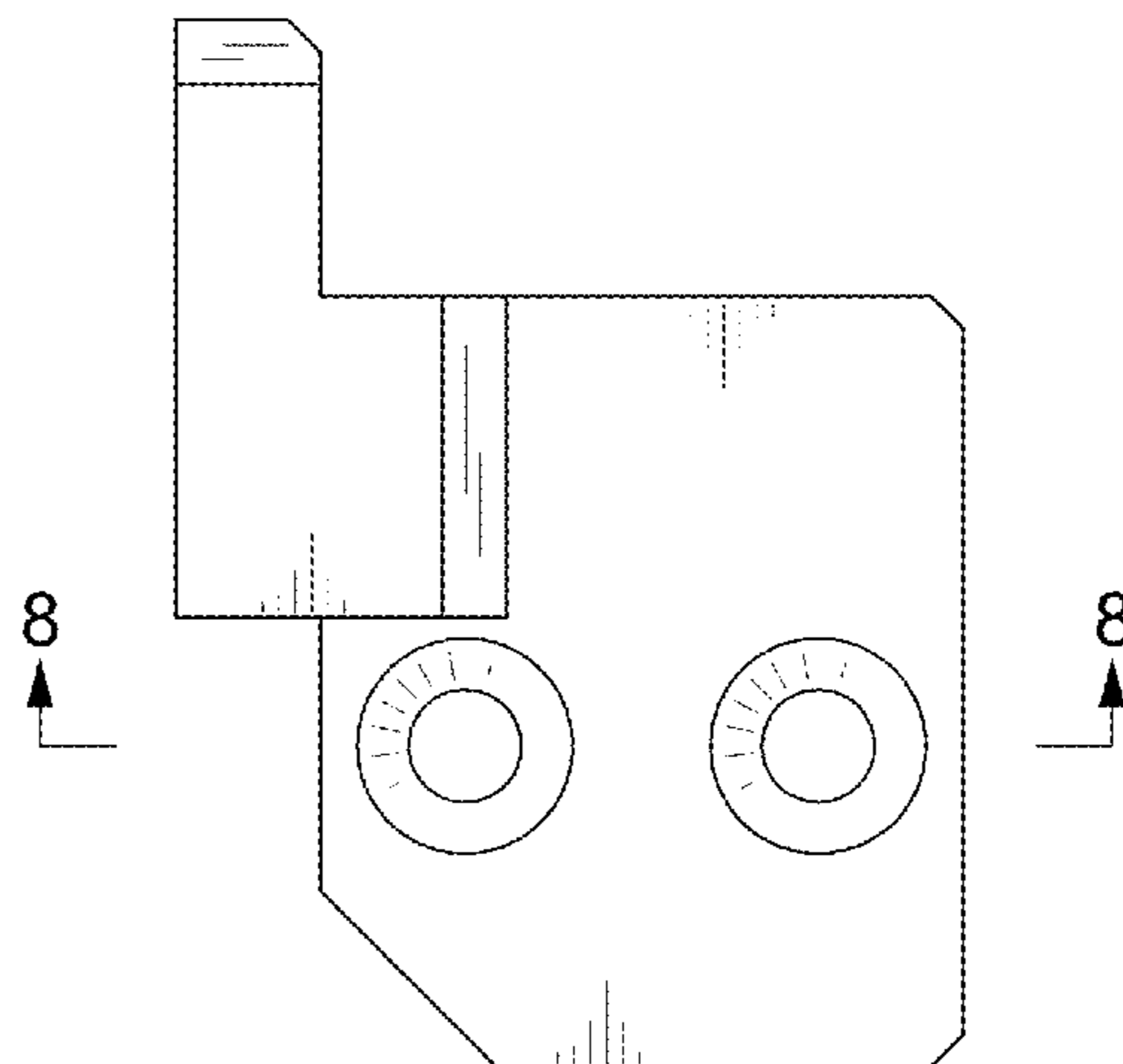
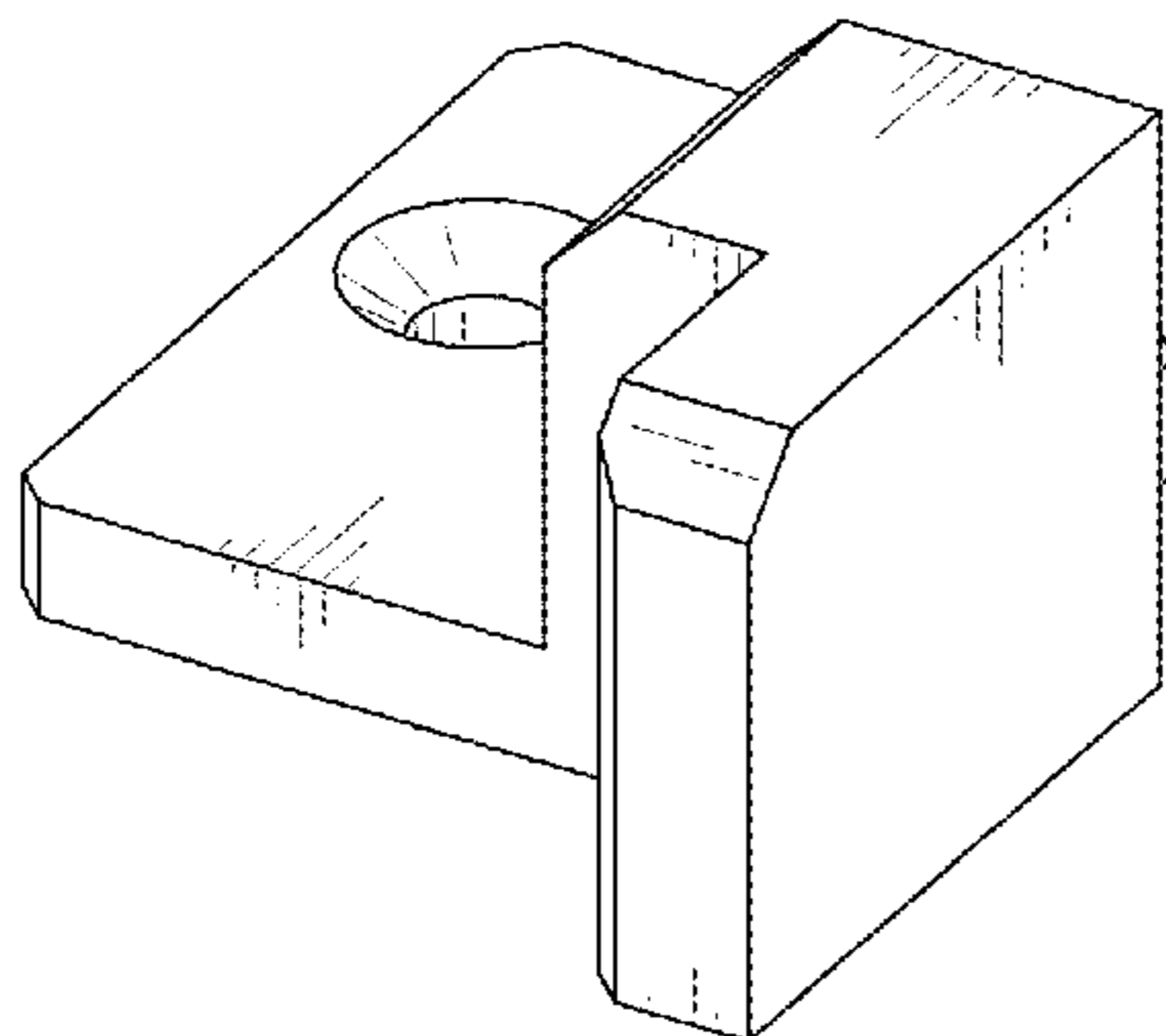
(57) **CLAIM**

The ornamental design for a cassette receiving tool for semiconductor manufacturing apparatus, as shown and described.

**DESCRIPTION**

FIG. 1 is a front, top, and left side perspective view of a cassette receiving tool for semiconductor manufacturing apparatus, showing my new design;  
FIG. 2 is a front elevational view thereof;  
FIG. 3 is a rear elevational view thereof;  
FIG. 4 is a left side elevational view thereof;  
FIG. 5 is a right side elevational view thereof;  
FIG. 6 is a top plan view thereof;  
FIG. 7 is a bottom plan view; and,  
FIG. 8 is a cross sectional view taken along line 8-8 in FIG. 2.

**1 Claim, 3 Drawing Sheets**



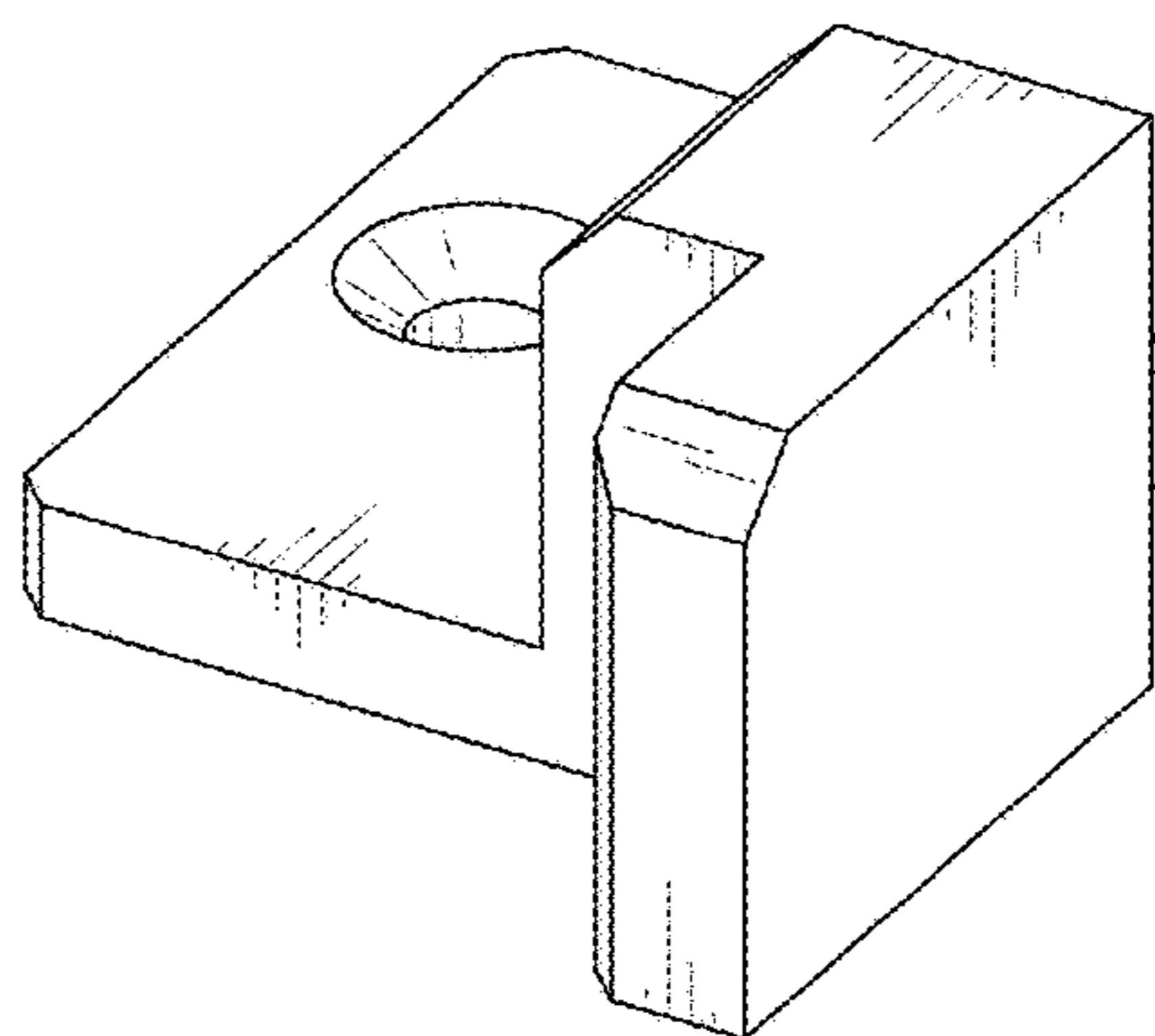


FIG. 1

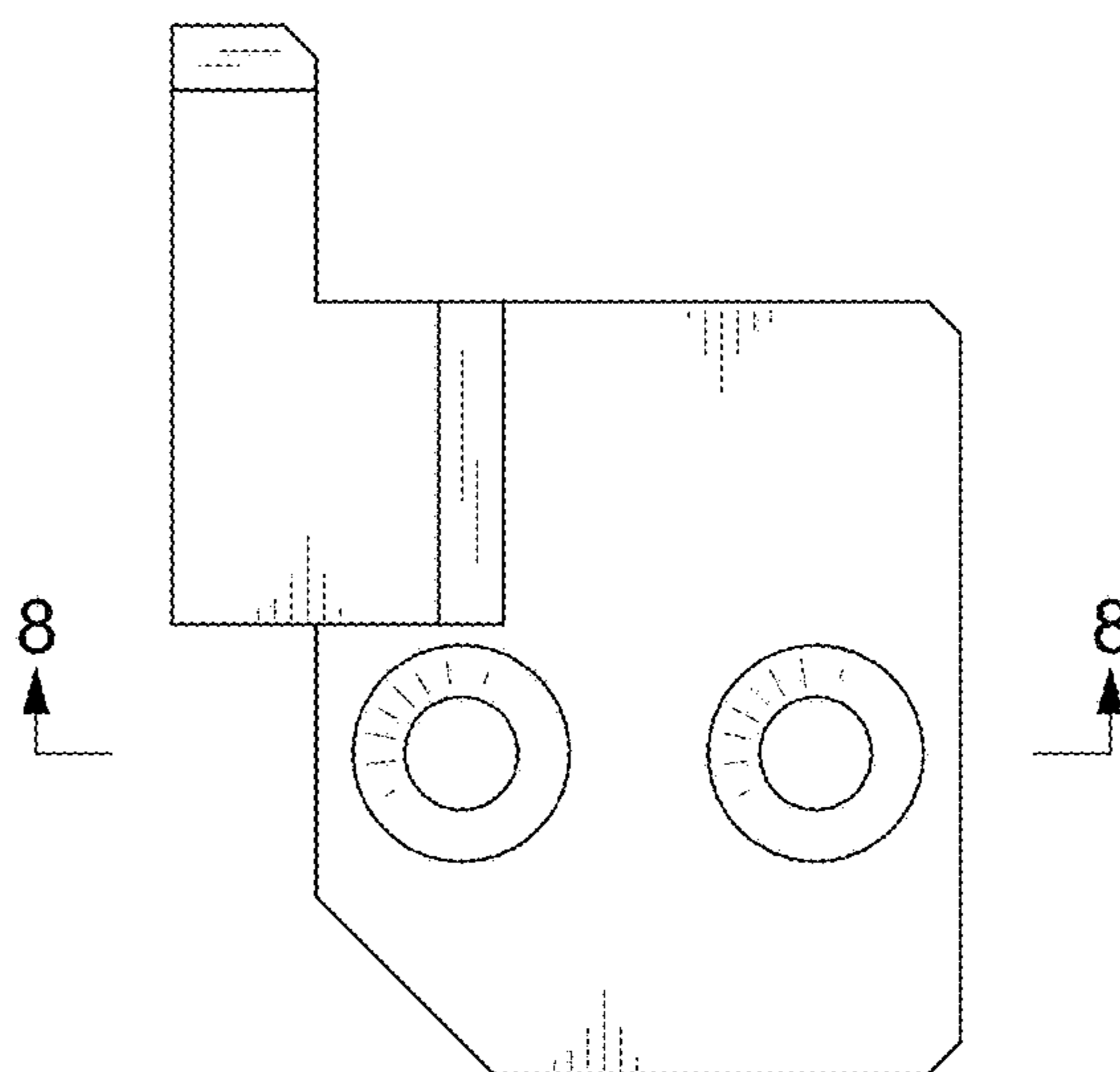


FIG. 2

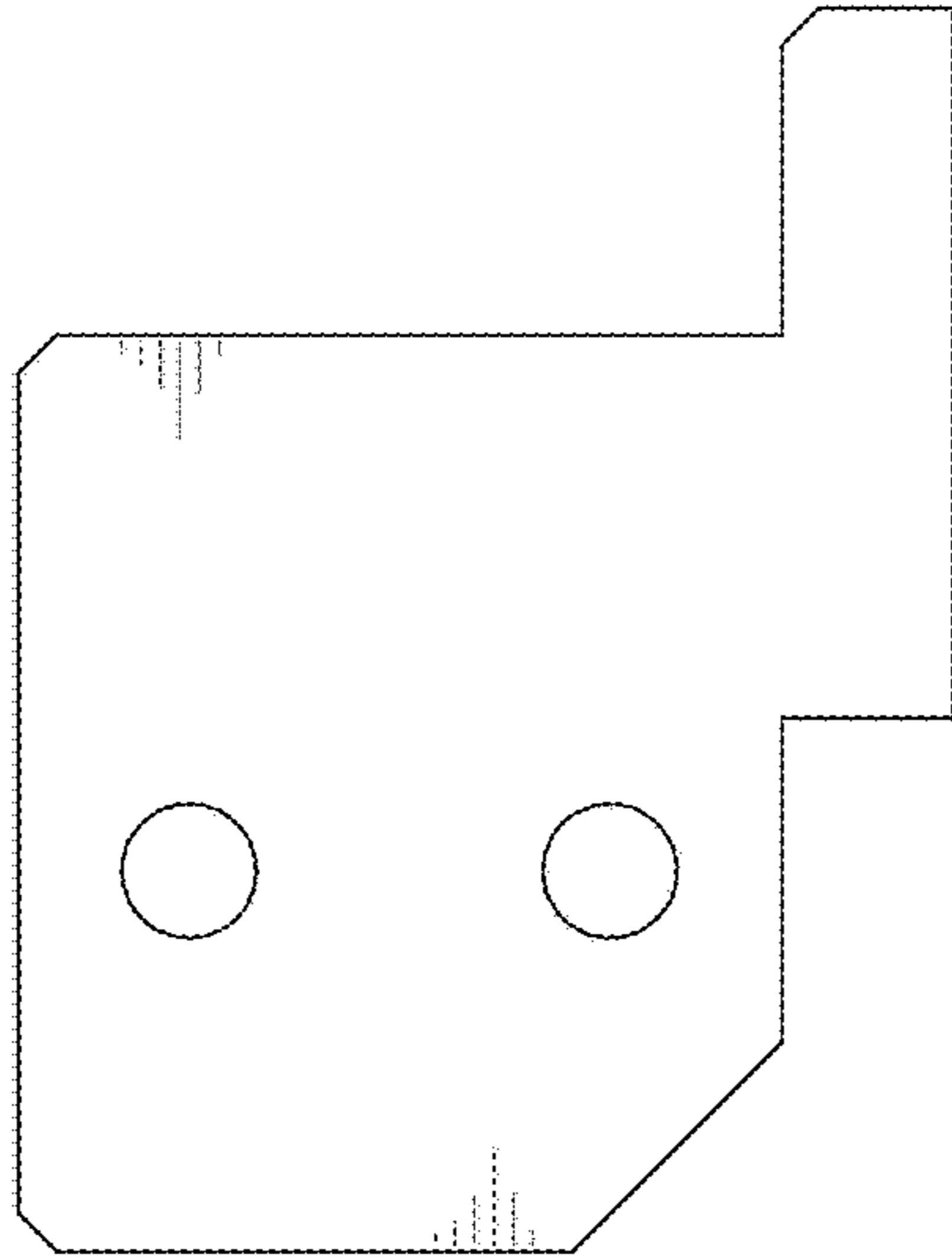


FIG. 3

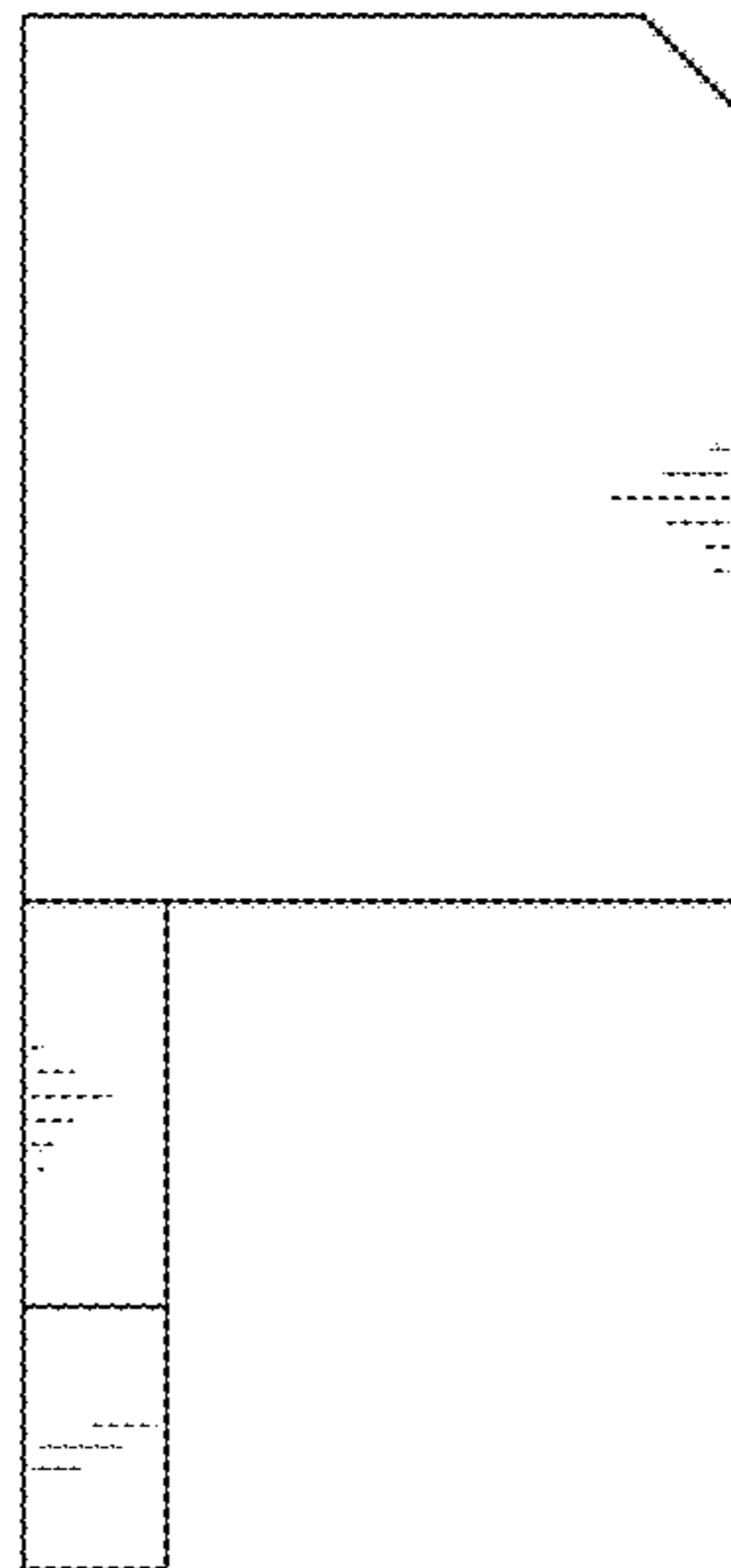


FIG. 4

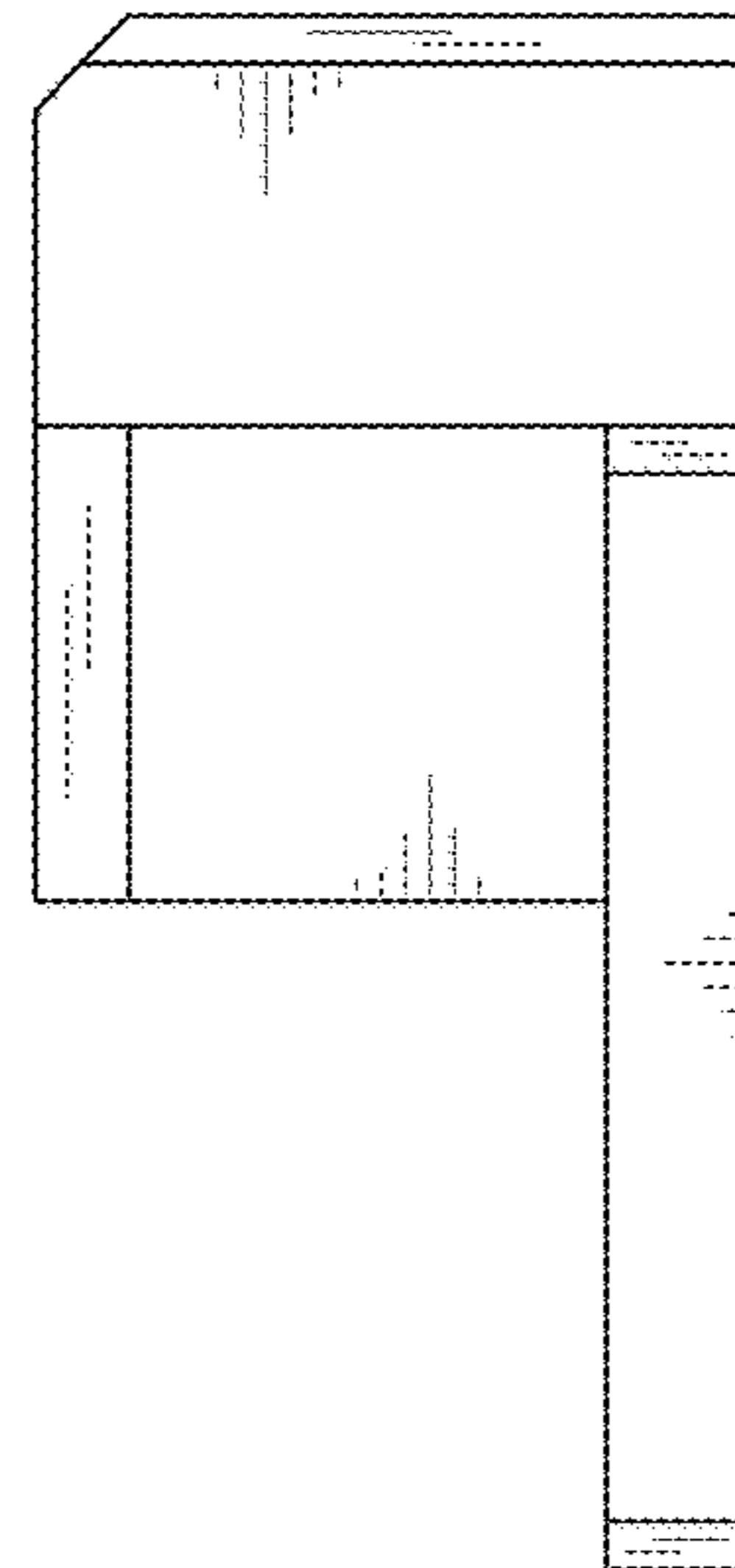


FIG. 5

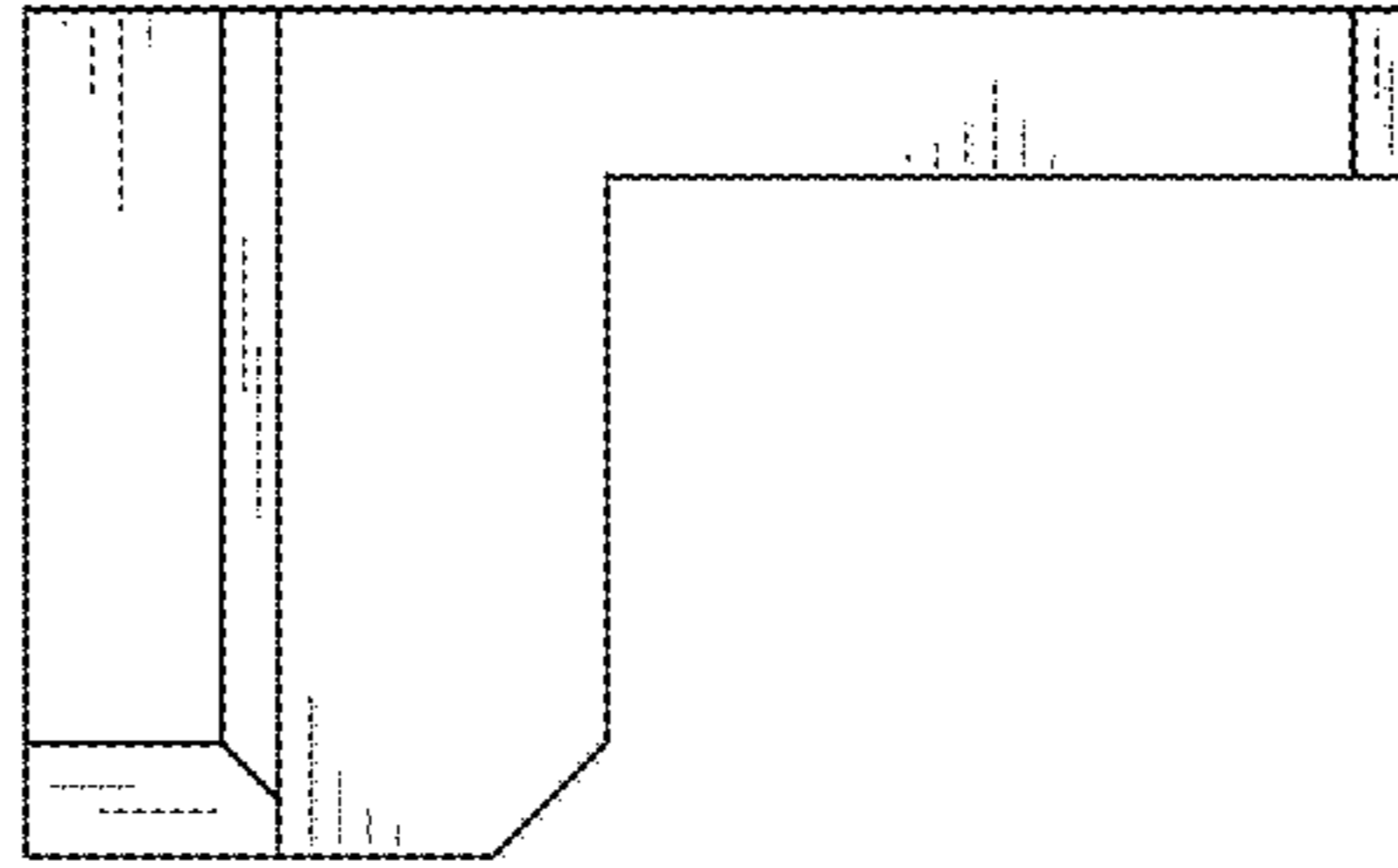


FIG. 6

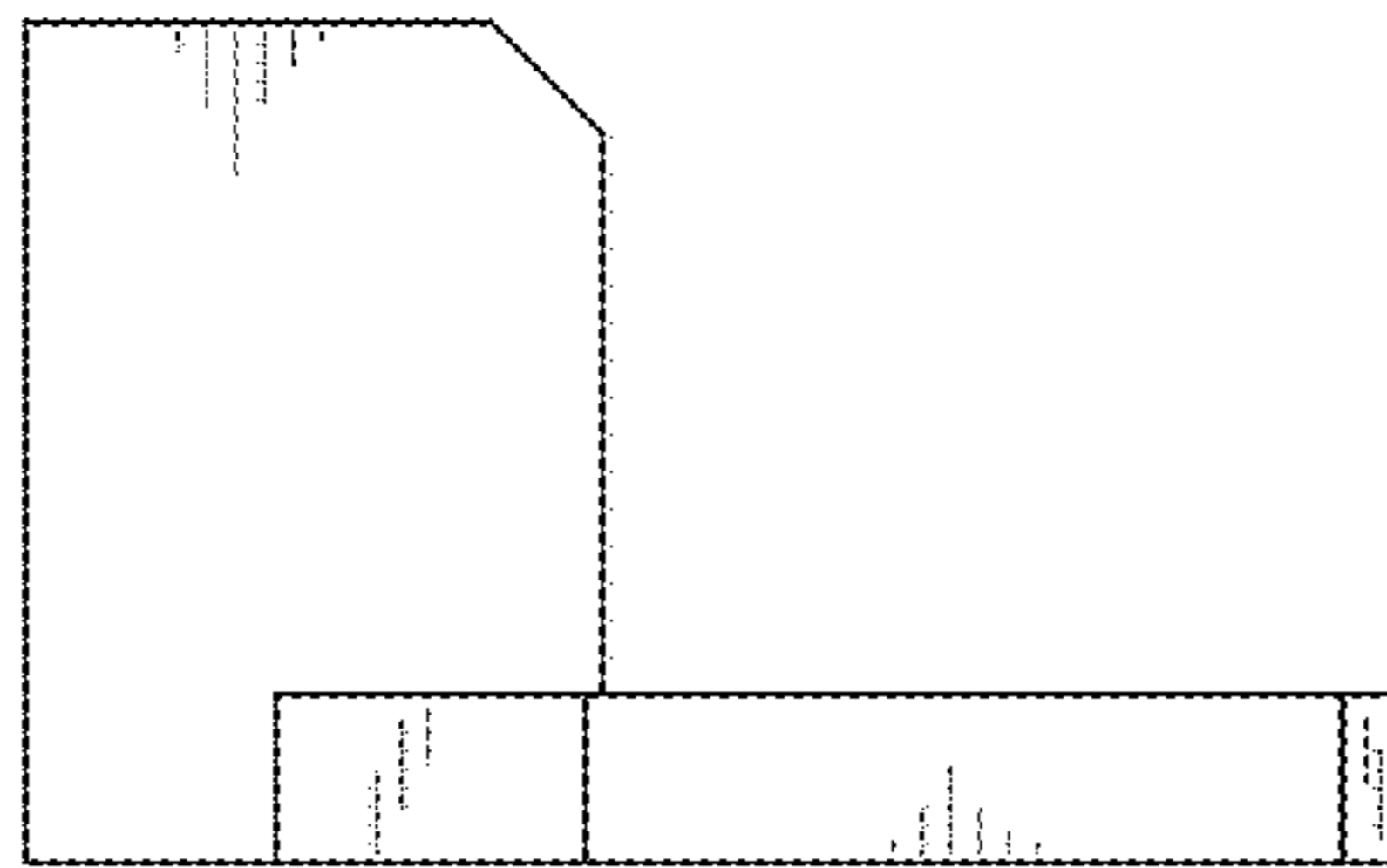


FIG. 7

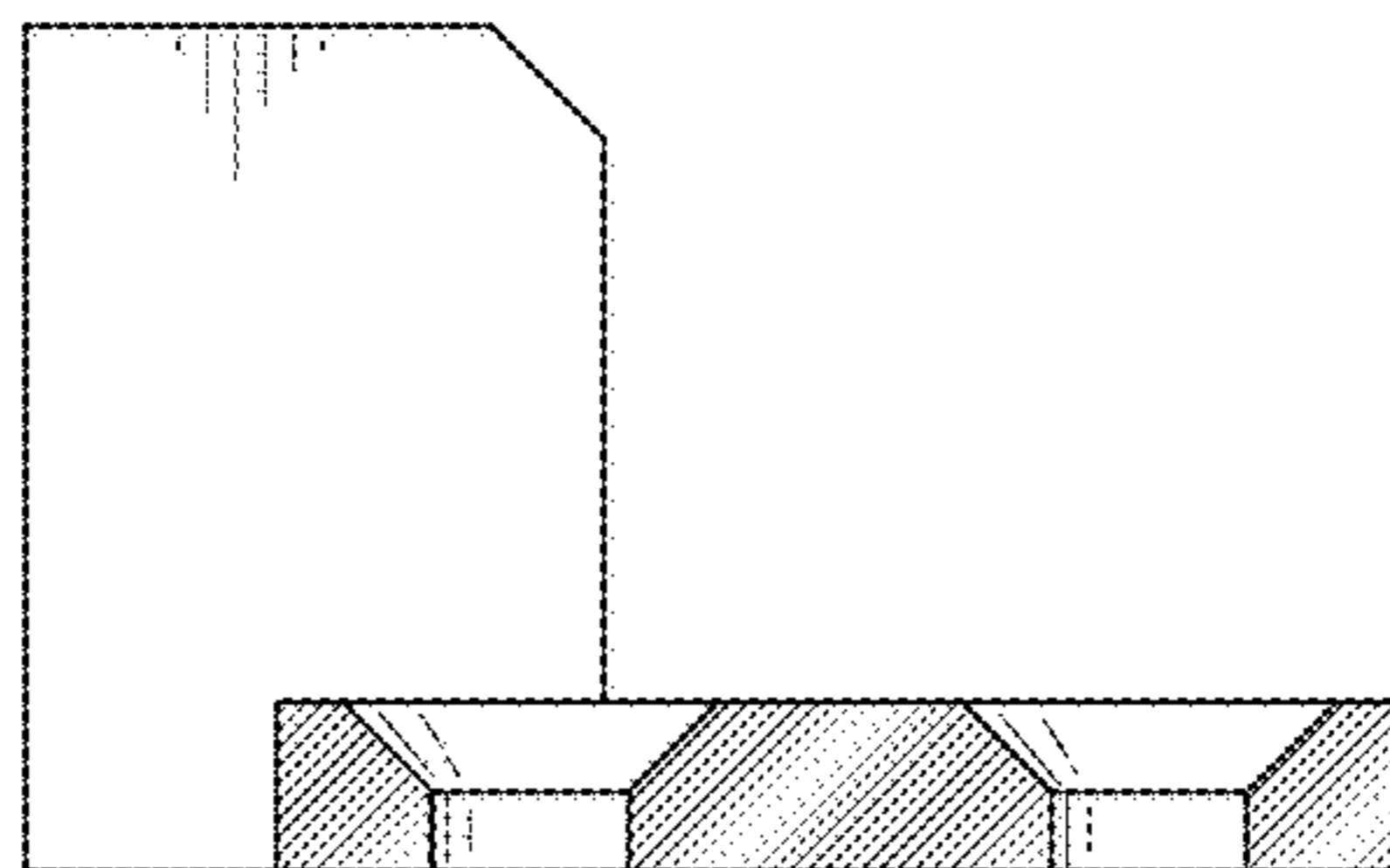


FIG. 8